

## Dymax 9001v3.0 Low Modulus Clear Microencapsulant

Category : Polymer , Adhesive , Thermoset

**Material Notes:**

High Performance Light-Curing Adhesives and Coatings for Electronic Assembly  
Dymax 9001v3.0 Low Modulus Clear Microencapsulant  
Lowest stress potting and encapsulation on ceramic, FR-4 or flexible PCBs as well as flip chip, IC cards and other high flow applications  
Cure Type: UV/Visible Typical Use: High flow for IC cards and flip chip assembly

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Dymax-9001v30-Low-Modulus-Clear-Microencapsulant.php](http://www.lookpolymers.com/polymer_Dymax-9001v30-Low-Modulus-Clear-Microencapsulant.php)

Physical Properties	Metric	English	Comments
Viscosity	400 cP	400 cP	

Optical Properties	Metric	English	Comments
Transmission, Visible	90 %	90 %	clear; thickness not quantified

Processing Properties	Metric	English	Comments
Cure Time	0.0333 - 0.167 min	0.000556 - 0.00278 hour	10-20 mil thick layers cured with Dymax 5000-EC at 2 inches. Thicker layers may require more cure time.

Descriptive Properties	Value	Comments
Color	Clear	

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